ALPHA & OMEGA SEMICONDUCTOR

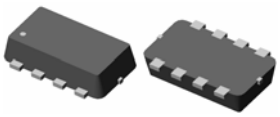
AON4605
Complementary Enhancement Mode Field Effect Transistor

General Description
The AON4605 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs form a high-speed power inverter, suitable for a multitude of applications. Standard Product AON4605 is Pb-free (meets ROHS & Sony 259 specifications).

Features
n-channel **p-channel**

V_{DS} (V) = 30V -30V
I_D = 4.3A -3.4A (V_{GS}= ±10V)

$R_{DS(ON)}$ < 65mΩ < 110mΩ (V_{GS} = ±10V)
$R_{DS(ON)}$ < 115mΩ < 180mΩ (V_{GS} = ±4.5V)



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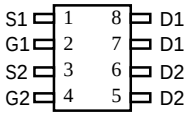

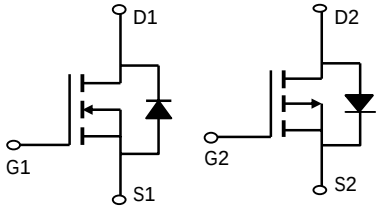

n-channel p-channel

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current [A,F]	T_A=25°C	I_D	4.3	-3.4	A
	T_A=70°C		3.4	-2.7	
Pulsed Drain Current [B]		I_{DM}	12	-12	
Power Dissipation	T_A=25°C	P_D	1.9	1.9	W
	T_A=70°C		1.2	1.2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics: n-channel

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	51.5	65	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		82	100	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	37	50	°C/W

Thermal Characteristics: p-channel

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	51.5	65	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		82	100	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	37	50	°C/W

N-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1	1.9	3	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	12			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=4.3A		52	65	mΩ
		T_J=125°C		78		
		V_{GS}=4.5V, I_D=2.5A		90	115	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=4.3A		5.4		S
V_{SD}	Diode Forward Voltage	I_S=1A		0.8	1	V
I_S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		238	310	pF
C_{oss}	Output Capacitance			50		pF
C_{rss}	Reverse Transfer Capacitance			30		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		2.3	3.5	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=4.3A		6.5	8.5	nC
Q_g(4.5V)	Total Gate Charge			3.1	4	nC
Q_{gs}	Gate Source Charge			1.2		nC
Q_{gd}	Gate Drain Charge			1.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=3.5Ω, R_{GEN}=3Ω		3.3		ns
t_r	Turn-On Rise Time			2.5		ns
$t_{D(off)}$	Turn-Off DelayTime			13.2		ns
t_f	Turn-Off Fall Time			1.7		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=4.3A, dI/dt=100A/µs		9.4	12	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=4.3A, dI/dt=100A/µs		3.5		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

F.The current rating is based on the t ≤ 10s thermal resistance rating.

Rev 1 : Dec 2006

TYPICAL N-CHANNEL ELECTRICAL AND THERMAL CHARACTERISTICS

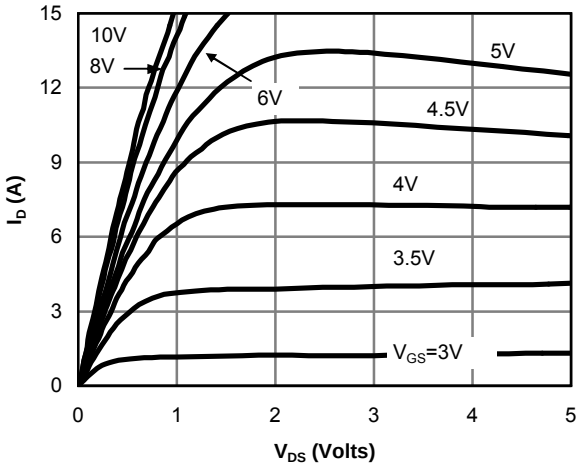

Figure 1: On-Region Characteristics

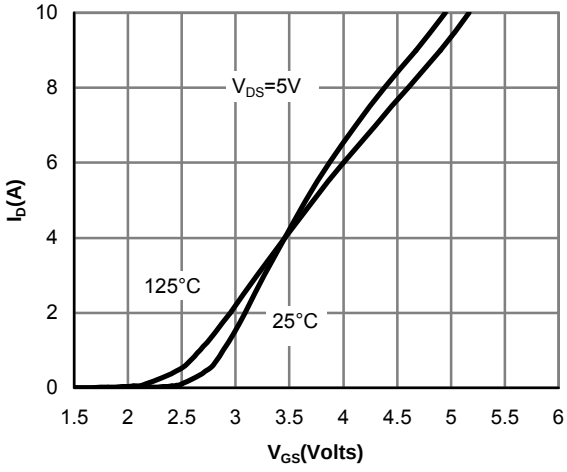

Figure 2: Transfer Characteristics

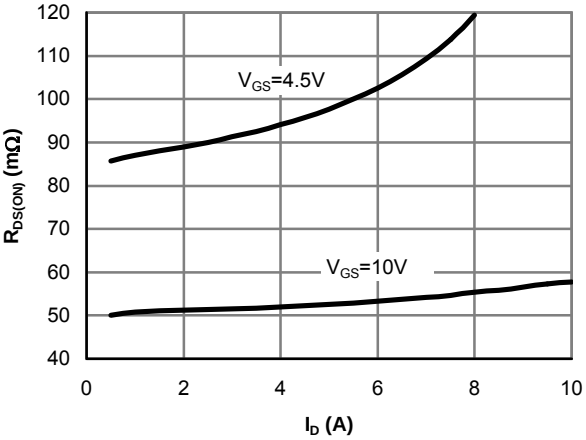

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

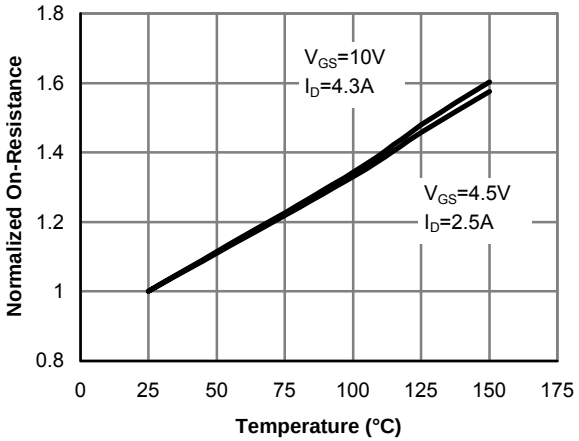

Figure 4: On-Resistance vs. Junction Temperature

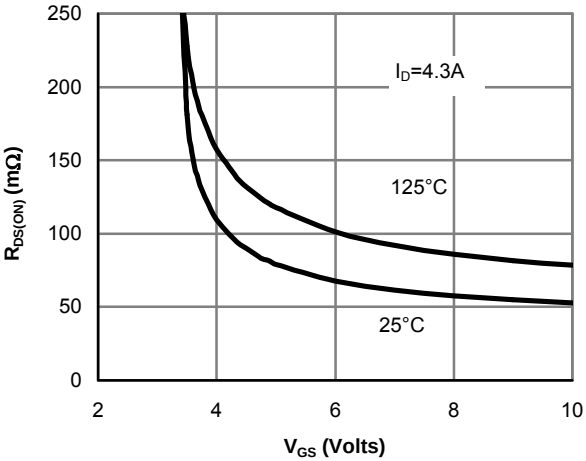

Figure 5: On-Resistance vs. Gate-Source Voltage

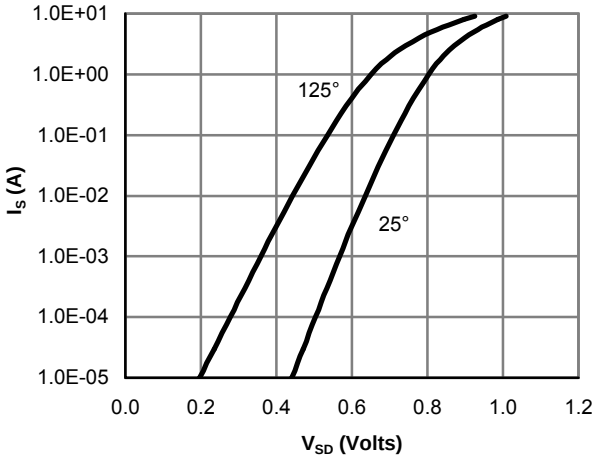

Figure 6: Body-Diode Characteristics

TYPICAL N-CHANNEL ELECTRICAL AND THERMAL CHARACTERISTICS

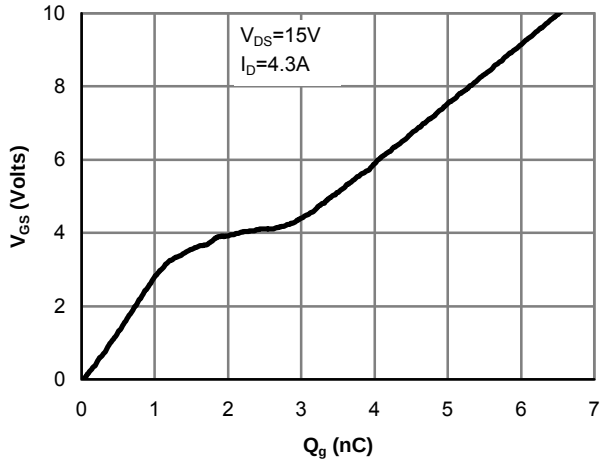

Figure 7: Gate-Charge Characteristics

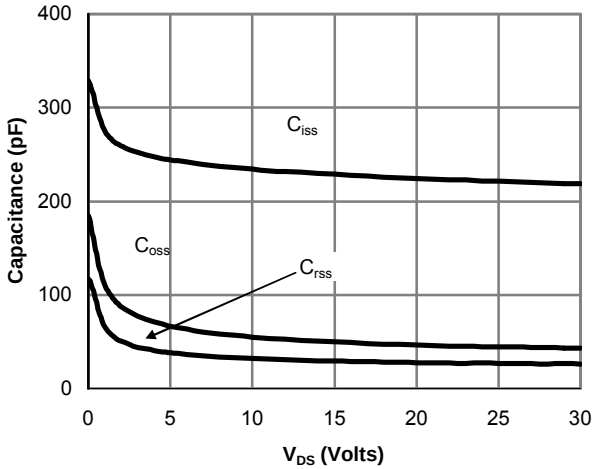

Figure 8: Capacitance Characteristics

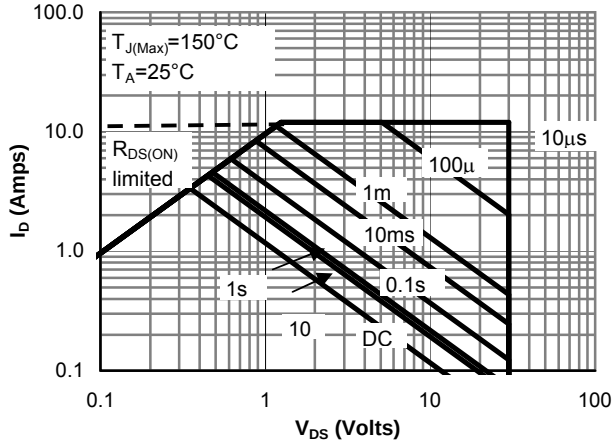

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

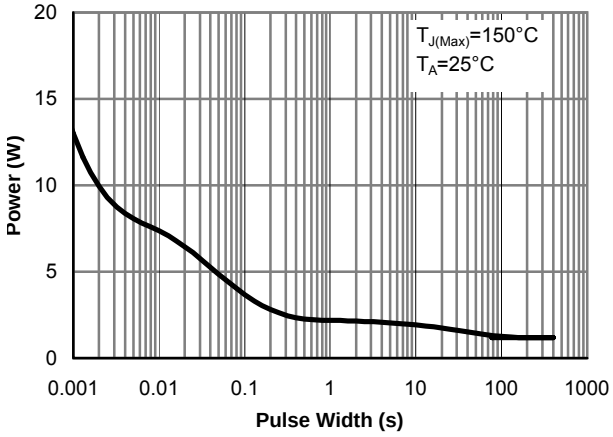

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

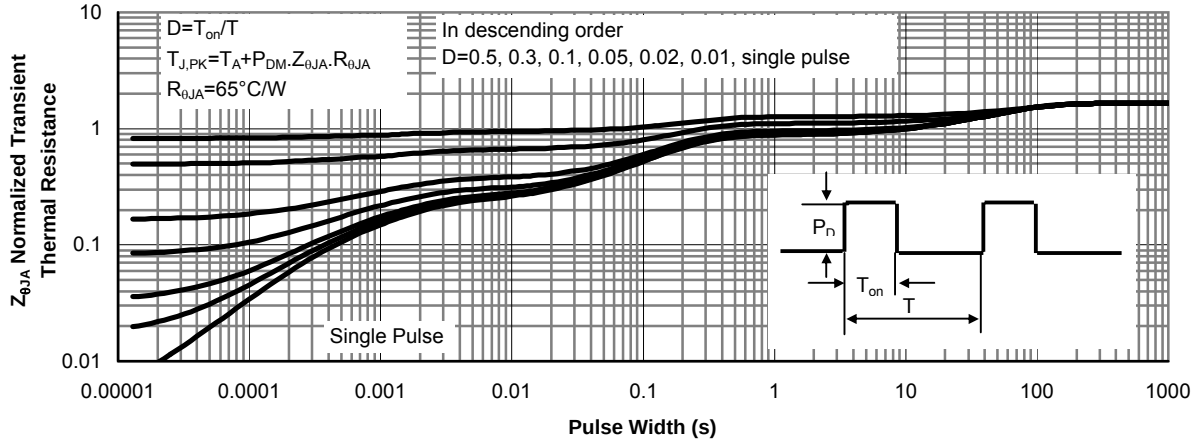

Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-30V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1	-2	-3	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS}=-5V	-12			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-3.4A		88	110	mΩ
		T_J=125°C		122		
		V_{GS}=-4.5V, I_D=-2A		138	180	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-3.4A		4.5		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.8	-1	V
I_S	Maximum Body-Diode Continuous Current				-2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, f=1MHz		290	350	pF
C_{oss}	Output Capacitance			65		pF
C_{rss}	Reverse Transfer Capacitance			44		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		4.3	6.5	Ω
SWITCHING PARAMETERS						
Q_g(10)	Total Gate Charge(10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-3.4A		5.8	7	nC
Q_g(4.5)	Total Gate Charge(4.5V)			3	4	nC
Q_{gs}	Gate Source Charge			0.78		nC
Q_{gd}	Gate Drain Charge			1.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-15V, R_L=4.4Ω, R_{GEN}=3Ω		7		ns
t_r	Turn-On Rise Time			6		ns
$t_{D(off)}$	Turn-Off DelayTime			15		ns
t_f	Turn-Off Fall Time			7.5		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-3.4A, dI/dt=100A/µs		12.5	15	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-3.4A, dI/dt=100A/µs		5.5		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

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F.The current rating is based on the t ≤ 10s thermal resistance rating.

Rev 1 : Dec 2006

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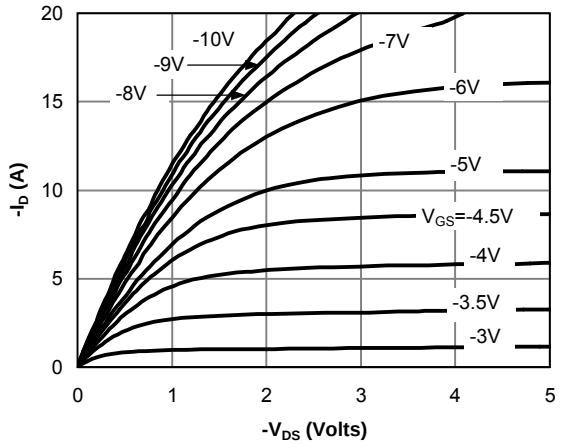

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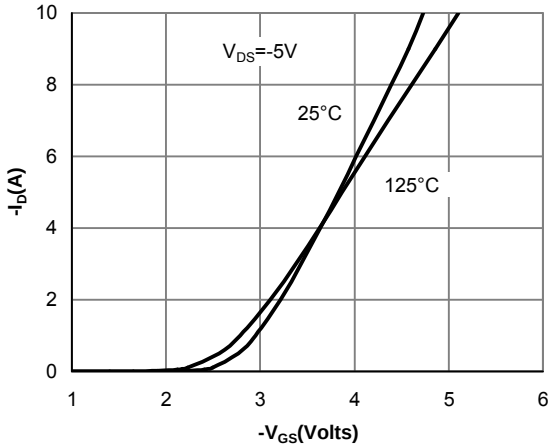

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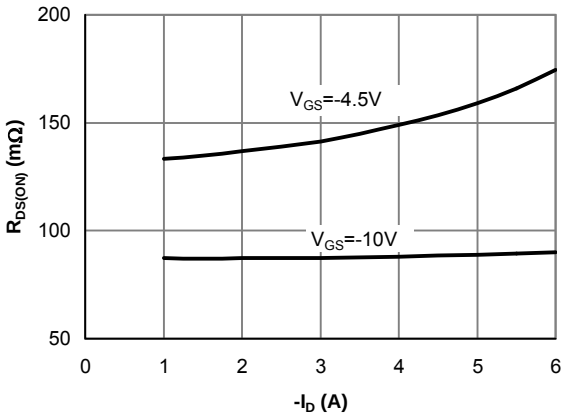

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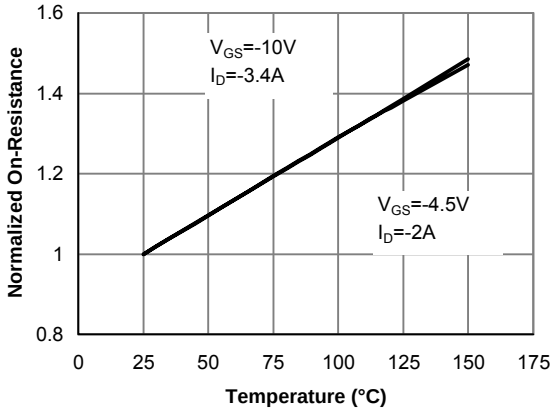

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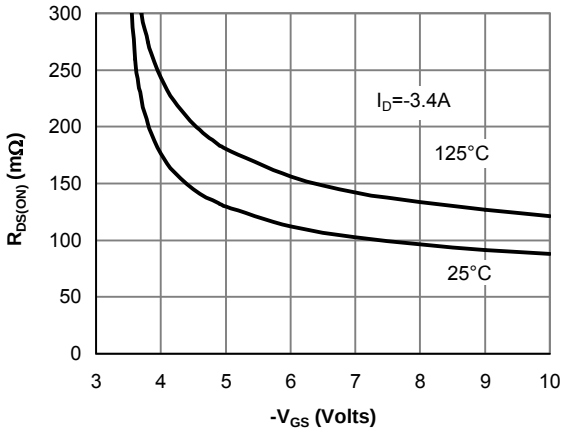

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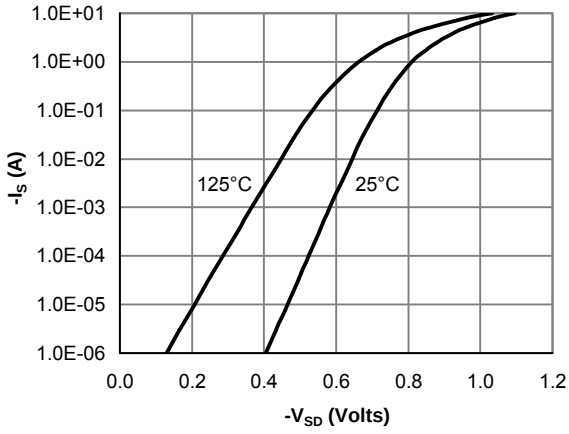

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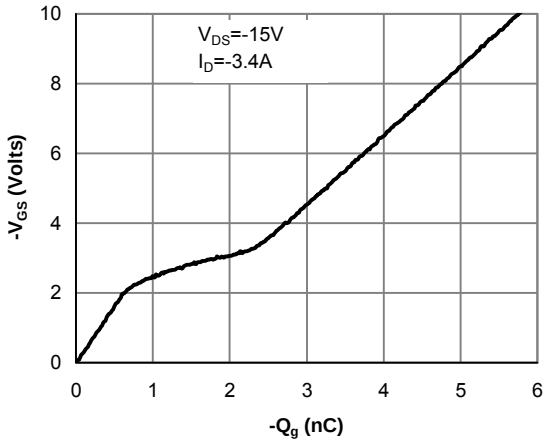

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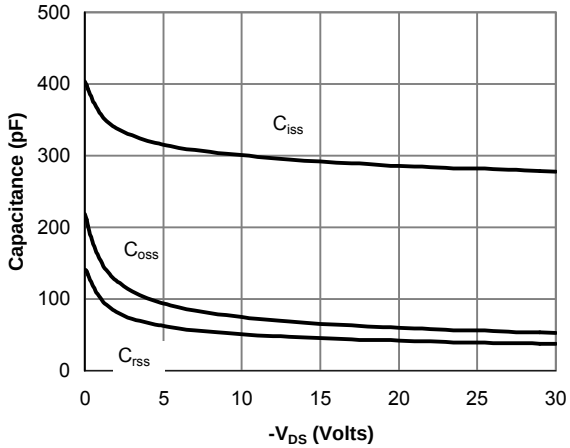

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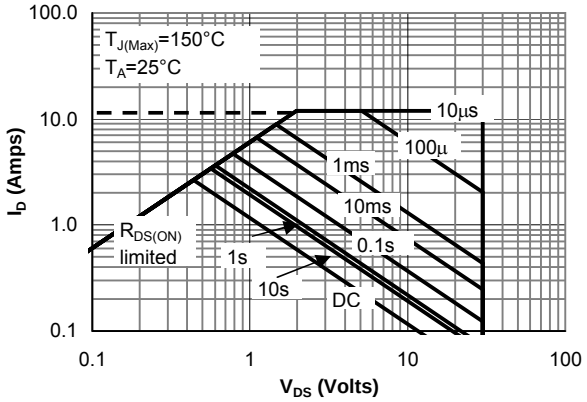

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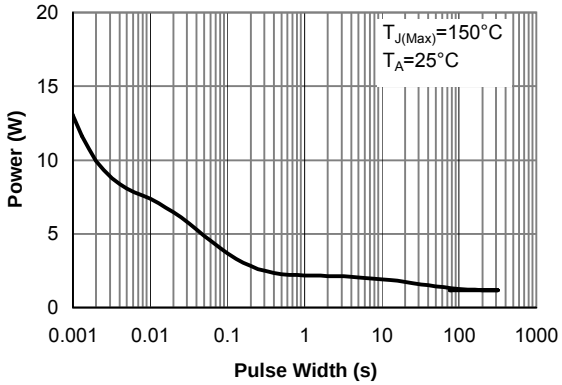

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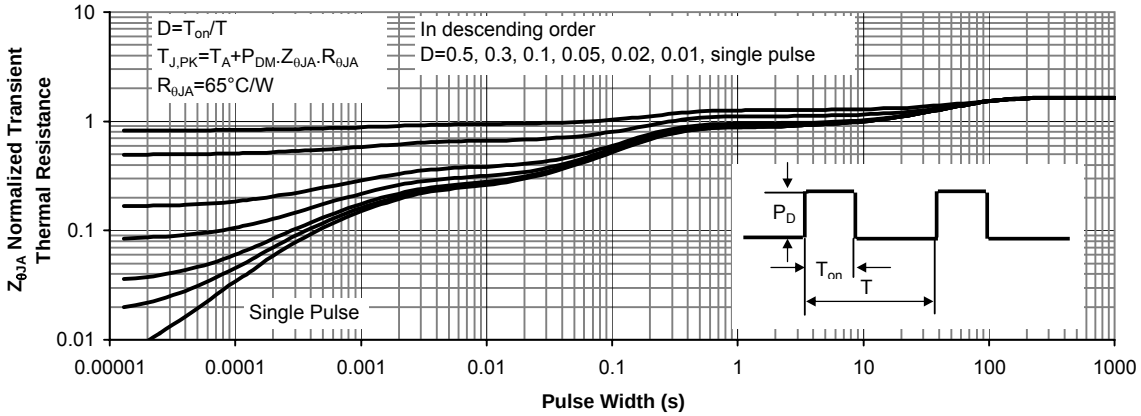

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